Customer Information Notification

202304017I : Update Testflow information for Token in PPAP documentation

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 24, 2023 **Effective date:May 21, 2023**

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Management summary

This Information Note informs about an update of the documentation of the production test flow for the Token product family. The final test will be carried out at 25C instead of 85C. The three temperature test will be maintained.

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[ ]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[ ]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[ ]Wafer Fab Location	[ ]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[X]Other: Documentation			

PCN Overview

Description

The objective of this information note is to inform about updated test flow documentation for the Token product family.
The final production test for Token product family will be carried out at 25C (room temperature) instead of 85C (hot temperature). The three temperature test will be maintained, as the wafer test process includes minimum and maximum specified temperature corners.
There is no change on the product and the tester platform and test coverage will remain the same. A description of the test flow and its validation is attached to this information note (see 'Attached Files').

Reason

The documentation has been updated to reflect the modified test temperature assignment.
To support increasing production volume for the Token family, the test flow is standardized by performing the final production test at room temperature.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
No change of product

Additional information

Additional documents: view online

Remarks

The ZVEI DeQuMa is not attached, since none of the items is applicable. This note shall update the documentation only.
Remark: The introduction of the test flow as described will start by end of May 2023. All Token products will be considered step by step; hence the transition of all products will take until Q4/2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.
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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
NCF29A1EHN/0500IJ	935305594118	NCF29A1EHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A1MHN/0500IJ	935305595118	NCF29A1MHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A1VHN/0500IJ	935305596118	NCF29A1VHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A1XHN/0500IJ	935305597118	NCF29A1XHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A1XHN/0504GJ	935305661118	NCF29A1XHN/0504G	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A1MHN/0504GJ	935305662118	NCF29A1MHN/0504G	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A2EHN/0500IJ	935305598118	NCF29A2EHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A2MHN/0500IJ	935305599118	NCF29A2MHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A2VHN/0500IJ	935305601118	NCF29A2VHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A2XHN/0500IJ	935305602118	NCF29A2XHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A3VHN/0500IJ	935305603118	NCF29A3VHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A3MHN/0500IJ	935305659118	NCF29A3MHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A3MHN/0500OJ	935308155118	NCF29A3MHN/0500O	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A3MHN/0500VJ	935330415118	NCF29A3MHN/0500V	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
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NCF29A4MHN/0500IJ	935305654118	NCF29A4MHN/0500I	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A4MHN/0510OJ	935306123118	NCF29A4MHN/0510O	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A4XHN/0500VJ	935308841118	NCF29A4XHN/0500V	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2
NCF29A4VHN/0500EJ	935308959118	NCF29A4VHN/0500E	TOKEN	H(V)QFN32	SOT617-3	RFS	No	BLC2